



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUA250N04S6N005	Issued	08. April 2022
MA#	MA005354076		
Package	PG-HSOF-5-4	Weight*	373.33 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.498	0.67	0.67	6691	6691
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.02		154	
	non noble metal	iron	7439-89-6	0.191	0.05		512	
	non noble metal	copper	7440-50-8	191.056	51.18	51.25	511763	512429
wire	noble metal	gold	7440-57-5	0.033	0.01	0.01	88	88
encapsulation	inorganic material	zinc oxide	1314-13-2	1.390	0.37		3722	
	miscellaneous	miscellaneous	-	5.559	1.49		14890	
	plastics	epoxy resin	-	20.846	5.58		55837	
	inorganic material	silicon dioxide	60676-86-0	111.176	29.78	37.22	297799	372248
lead finish	non noble metal	tin	7440-31-5	3.673	0.98	0.98	9838	9838
plating	noble metal	silver	7440-22-4	0.015			41	41
solder	non noble metal	tin	7440-31-5	0.064	0.02		172	
	noble metal	silver	7440-22-4	0.080	0.02		215	
	non noble metal	lead	7439-92-1	3.059	0.82	0.86	8194	8581
heat sink clip	inorganic material	phosphorus	7723-14-0	0.010			27	
	non noble metal	iron	7439-89-6	0.034	0.01		90	
	non noble metal	copper	7440-50-8	33.587	9.00	9.01	89967	90084
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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